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PATENT

#7B Amdt. N/A

M. Brunson

8/15/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ross Addinall, et al.
Serial No.: 09/639,288
Filed: August 15, 2000
Title: INTEGRATED CIRCUIT DIE FOR WIRE BONDING
AND FLIP-CHIP MOUNTING
Grp./A.U.: 2814
Examiner: Phat X. Cao

Honorable Commissioner for Patents
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service
as first class mail in an envelope addressed to: Commissioner for Patents and Trademarks,
Washington, D.C. 20231, on 08/01/2002 (Date)
Stephane P. H.
(Printed or typed name of person signing the certificate)
Stephane P. H.
(Signature of the person signing the certificate)

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.116

In response to the Examiner's Action mailed June 4, 2002, please amend the above-identified
application as follows:

IN THE CLAIMS:

(1) Please amend Claim 1 as follows:

1. (Twice Amended) An integrated circuit die including first and second sets of conductive
pads for enabling external connections to be made to the integrated circuit, wherein each pad of said
first set is larger than each pad of said second set, there being at least a first predetermined center-to-

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